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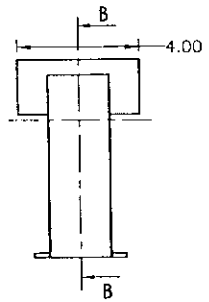
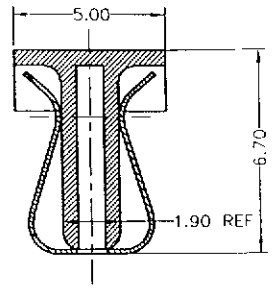
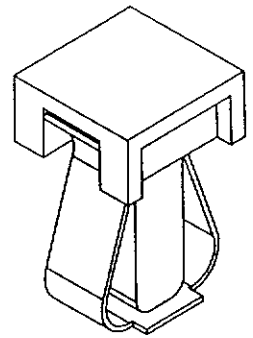
REVISIONS				
SYM	ECN	DESCRIPTION	DATE	APPROVED
B	HK2400	RELEASE TO CUSTOMER	12/05/02	IP

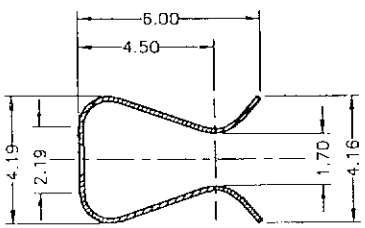
CONTROLLED DOCUMENT
0 5 DEC 2002



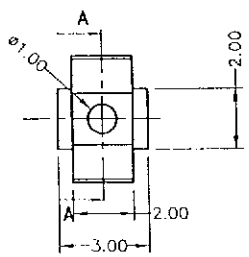


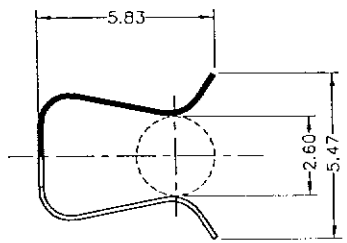
SECTION B-B





SECTION A-A





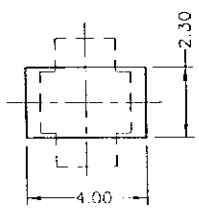
working position

PACKING METHOD

AMPHENOL EAST ASIA LIMITED
ENGINEERING DEPARTMENT
DOCUMENT CONTROL
0 5 DEC 2002
RECEIVED

NOTES:

1. MATERIAL:BeCu, C17410,HTS,0.15±0.02mm thick.
2. FINISH:15 MICROINCH(0.381 MICRON) GOLD PLATE AT MATING AREA.
   50-100 MICROINCH (1.27-2.54 MICRON)NICKEL UNDERPLATED ALL OVER.
3. NORMAL FORCE: 100g MIN AT WORKING POSITION.
4. Packing : tape & reel



RECOMMENDED PCB MOUNTAING PATTERN

CUSTOMER DRAWING

UNLESS OTHERWISE SPECIFIED TOLERANCES			APPROVAL	DATE	Amphenol
	U.S.	METRIC	DRAWN		Amphenol East Asia Limited Manufacturing Operation
.X +/-		0.30	CHECKED		
.XX +/-		0.20	CHECKED		TITLE CUSTOMER DRAWING FOR ANTENNA CONTACT
.XXX +/-					
FRACTIONS +/-			DRAWING FILE DRAWING\SP\CSP-0205-801		
ANGLES +/-		5°			
FOR MATERIALS AND FINISHES SEE NOTES					
REMOVE SHARP EDGES			ANGLE OF PROJECTION		SIZE A3 / DRAWING NO. C SP-0205-801 / REV. B
DIMENSIONS					
U.S.	INCHES				SCALE NONE / SHEET 1 OF 1
(METRIC)	(MM)				

☐ STMS ☐ MLDM ☒ ASS'Y ☒ Q.A. ☐ MAT'L
☐ PUR. ☐ SALES ☒ OTHERS Sales